

## Title (en)

METHOD FOR COATING METAL SURFACES USING AN AQUEOUS COMPOUND HAVING POLYMERS, THE AQUEOUS COMPOUND, AND USE OF THE COATED SUBSTRATES

## Title (de)

VERFAHREN ZUR BESCHICHTUNG VON METALLISCHEN OBERFLÄCHEN MIT EINER WÄSSERIGEN, POLYMERE ENTHALTENDEN ZUSAMMENSETZUNG, DIE WÄSSERIGE ZUSAMMENSETZUNG UND VERWENDUNG DER BESCHICHTETEN SUBSTRATE

## Title (fr)

PROCÉDÉ POUR LE REVÊTEMENT DE SURFACES MÉTALLIQUES PAR UNE COMPOSITION AQUEUSE CONTENANT DES POLYMÈRES, COMPOSITION AQUEUSE ET UTILISATION DE SUPPORTS AINSI REVÊTUS

## Publication

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## Application

**EP 08717366 A 20080304**

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## Abstract (en)

[origin: CA2680242A1] The invention relates to a method for coating a metal surface using an aqueous composition, wherein in addition to water the composition also comprises a) an organic film former as the main component, wherein 70 to 100 wt.% of the content of synthetic resin(s) in the organic film former is formed by at least one water soluble or/and water dispersed synthetic resin in the form of polymers, copolymers, block copolymers, or/and graft copolymers based on synthetic resins, selected from the group consisting of polycarbonate, polyurethane, ionomer, poly(meth)acrylate, polyester, polyether, or/and polystyrene, wherein the polycarbonate and polyurethane content is at least 10 wt.-% each, b) at least one long-chained alcohol as a film former additive for the organic film former, c) at least one cross-linking agent, d) at least one lubricant, and e) at least one substance based on silane, silicic acid, or/and siloxane or/and at least one inorganic compound in particle form having a mean particle diameter in the range of 0.005 to 0.3  $\mu\text{m}$ , measured on the scanning electron microscope, and f) optionally at least one organic corrosion inhibitor, at least one organic solvent or/and at least one additive, wherein the metal surface is brought in contact with the aqueous composition, and a polymer film is formed on the metal surface, having a layer thickness within the range of 0.01 to 10  $\mu\text{m}$ . The invention further relates to a corresponding aqueous composition.

## IPC 8 full level

**B05D 7/16** (2006.01); **C08G 18/44** (2006.01); **C08K 5/5435** (2006.01); **C08L 69/00** (2006.01); **C08L 75/06** (2006.01); **C09D 5/08** (2006.01); **C09D 7/63** (2018.01); **C09D 169/00** (2006.01); **C09D 175/06** (2006.01)

## CPC (source: EP US)

**B05D 1/02** (2013.01 - US); **B05D 1/18** (2013.01 - US); **B05D 1/28** (2013.01 - US); **B05D 1/30** (2013.01 - US); **B05D 1/40** (2013.01 - US); **B05D 1/42** (2013.01 - US); **B05D 3/02** (2013.01 - US); **B05D 3/06** (2013.01 - US); **B05D 3/061** (2013.01 - US); **B05D 3/065** (2013.01 - US); **B05D 3/067** (2013.01 - US); **B05D 5/00** (2013.01 - EP US); **B05D 7/14** (2013.01 - EP US); **B05D 7/16** (2013.01 - US); **B05D 7/52** (2013.01 - US); **B32B 1/08** (2013.01 - US); **B32B 15/08** (2013.01 - US); **C08G 18/44** (2013.01 - EP US); **C08L 75/04** (2013.01 - EP US); **C09D 5/002** (2013.01 - EP US); **C09D 5/08** (2013.01 - EP US); **C09D 7/63** (2017.12 - EP US); **C09D 167/00** (2013.01 - EP US); **C09D 169/00** (2013.01 - EP US); **C09D 175/04** (2013.01 - EP US); **B05D 3/0254** (2013.01 - EP US); **B05D 2202/00** (2013.01 - US); **B05D 2202/10** (2013.01 - EP US); **B05D 2202/25** (2013.01 - US); **B05D 2202/35** (2013.01 - US); **B05D 2202/45** (2013.01 - US); **C08K 3/011** (2017.12 - EP US); **C08K 5/0025** (2013.01 - EP US); **C08K 5/005** (2013.01 - EP US); **C08K 5/05** (2013.01 - EP US); **C08K 5/54** (2013.01 - EP US); **C08K 5/5435** (2013.01 - EP US); **C08K 7/18** (2013.01 - EP US); **C08L 83/04** (2013.01 - EP US); **C08L 91/06** (2013.01 - EP US); **C23C 2222/20** (2013.01 - EP US); **Y10T 29/49826** (2015.01 - EP US); **Y10T 428/1355** (2015.01 - EP US); **Y10T 428/259** (2015.01 - EP US); **Y10T 428/2962** (2015.01 - EP US); **Y10T 428/31663** (2015.04 - EP US)

## C-Set (source: EP US)

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2. **C09D 169/00 + C08L 2666/02**
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4. **C09D 169/00 + C08L 91/06**
5. **C09D 167/00 + C08L 91/06**
6. **C09D 167/00 + C08L 83/00**
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See references of WO 2008110480A1

## Cited by

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## DOCDB simple family (application)

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